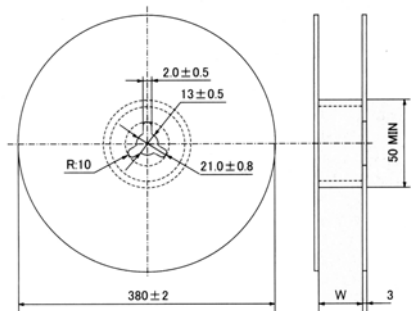


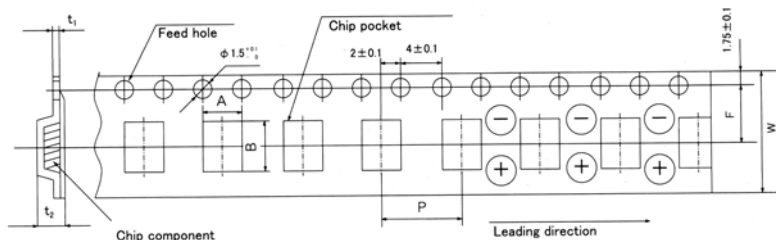
### ALUMINUM ELECTROLYTIC CAPACITORS

#### ● Packaging Specifications 零件產品包裝規格尺寸及數量



Dφ	W	Q'ty/Box (pcs)	Code
3 x 5.4	14	2,000	TR
4 x 5.4	14	2,000	
5 x 5.4	14	1,000	
6.3 x 5.4	18	1,000	
8 x 6.2	18	1,000	
8 x 10.2	26	500	
10 x 10.2	26	500	
12.5 x 13.5	34	200	
12.5 x 16	34	150	
16 (18) x 16.5	46	125	
16 (18) x 21.5	46	75	

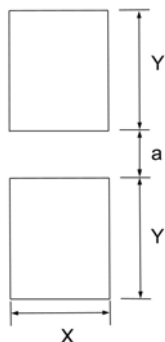
#### ● Chip Type Carrier Taping Specifications 零件產品規格尺寸



unit: mm

Dφ x L	W±0.3	A±0.2	B±0.2	P±0.1	F±0.1	t1±0.1	t2±0.1
3 x 5.4	12.0	3.4	3.5	8.0	5.5	0.4	5.8
4 x 5.4	12.0	4.7	4.6	8.0	5.5	0.4	5.8
5 x 5.4	12.0	5.7	5.7	12.0	5.5	0.4	5.8
6.3 x 5.4	16.0	7.0	7.0	12.0	7.5	0.4	5.8
8 x 6.2	16.0	8.7	8.7	12.0	7.5	0.4	6.8
8 x 10.2	24.0	8.7	8.7	16.0	11.5	0.4	11.0
10 x 10.2	24.0	10.7	10.7	16.0	11.5	0.4	11.0
12.5 x 13.5	32.0	14.0	14.0	24	14.2	0.5	14.0
12.5 x 16	32.0	14.0	14.0	24	14.2	0.5	16.3
16 x 16.5	44.0	17.5	17.5	28	20.2	0.5	16.8
16 x 21.5	44.0	17.5	17.5	28	20.2	0.5	21.8
18 x 16.5	44.0	19.5	19.5	32	20.2	0.5	16.8
18 x 21.5	44.0	19.5	19.5	32	20.2	0.5	21.8

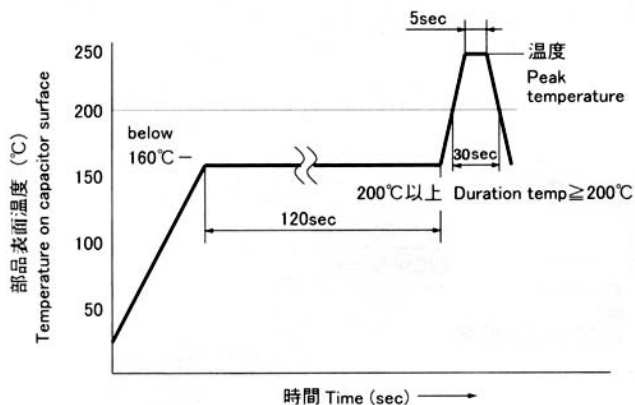
#### ● PC Board Layout Size PCB板佈局



unit: mm

Dφ x L	X	Y	a
3φ	1.6	2.2	0.8
4φ	1.6	2.6	1.0
5φ	1.6	3.0	1.4
6.3φ	1.6	3.5	2.1
8 x 6.2	2.5	4.0	2.1
8 x 10.2	2.5	3.5	3.0
10 x 10.2	2.5	4.0	4.0
12.5φ	2.5	6.0	5.0
16φ	3	6.5	8.0
18φ	3	7.5	8.0

#### ● Reflow Soldering Condition 迴錫爐溫度控制線



#### Note:

1. 預熱溫度應控制在 160°C, 120 秒內範圍。  
Preheat shall be made within 160°C, 120 seconds.
2. 爐溫 200°C 以上之時間操作應於 30 秒內完成。  
Operating duration for over 200°C shall be completed within 30 seconds.
3. 電容器表面最高溫度不能超過 230°C。  
Temperature at the surface of capacitor shall not exceed 230°C.